Unique ImmJET™ Wafer Processing

The WaferStorm® Platform

**Metal Lift-Off**
- Heated immersion tank
- High-pressure spray chamber
- Lift-off material filtration system
- High-pressure flow monitoring
- Low chemical consumption

**Photoresist/Dry Film Resist Strip**
- Heated, recirculating, solvent immersion tank
- High-pressure spray up to 3000 psi
- HPC needle and HPC fan-spray modes
- Flow rate monitoring system
- Low chemical consumption

**TSV Clean, Post-Etch Residue Removal**
- Heated immersion tank
- High-pressure spray chamber
- Low chemical consumption

**Flux Clean**
- Complete flux removal
- High yield process
WaferStorm is a solvent-based platform, available in customizable configurations. All WaferStorm systems are based on Veeco’s unique ImmJET technology, which provides improved performance at lower cost of ownership when compared with conventional wet-bench-only or spray-only approaches. The process combines equal soak time in the wet buffer tank for each wafer, followed by spray, and then a final step depending on the process being performed. This unique combination minimizes both spray time and chemistry use, and adds a significant level of control during wafer processing. The reduction in spray time results in increased throughput.

**WaferStorm is available for multiple processes, including:**

**TSV Clean**
- Complete sidewall polymer removal
- Complete photoresist removal
- Savings in process time

**Metal Lift-Off**
- Complete metal removal through material filtration station
- 50% lower chemical use

**Photoresist/Dry Film Resist Strip**
- Patented triple strained
- Resist removal

**Flux Clean**
- Complete flux removal
- High yield results